TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT								Docket No.					
			8377/ETCH/SILICON										
In	re A	pplicati	on of: M	lui, et al.		2 2004	H						
		Serial		Filing D	ate JAN	42 2004	Examiner	Group Art Unit					
Titl	6 .	10/666 METE		September 1		DIMES	SIONS DURING AN	1765 ETCH PROCESS					
Title: METHOD FOR CONTROLLING CRITICAL DIMESSIONS DURING AN ETCH PROCESS Address to:													
Commissioner for Patents Alexandria, VA 22313-1450													
					37 CFR	R 1.97(I	b)						
1.	⊠	The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits; or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.											
					37 CFR	R 1.97(c)						
2.		The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), but prior to the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by the statement or fee as indicated below.											
					37 CFR	R 1.97(d	d)						
3.		The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(c), but on or before payment of the issue fee and is accompanied by the statement and fee as indicated below.											
Required Statements and/or Fees Under 37 CFR 1.97(c) or (d)													
		No item of information in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the Information Disclosure Statement. (37 CFR 1.97(e)(2))											
		The fee set forth in 37 CFR 1.17(p). Please credit any overpayment or charge any insufficiencies to deposit account number 20-0782.											
					37 CFR	§1.704	(d)						
4.		Each item of information in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart application and this communication was not received by any individual designated in 37 CFR §1.56(c) more than thirty days prior to the filing of the Information Disclosure Statement.											
	1/2 Can 19, 2004												
			oada, Esq.		7		Certificate of Mailin	g by First Class Mail					
Reg. No. 45,150 I certify that this document is being deposited on /-20-2009 with the U.S. Postal Service as first class mail under 37 CFR §1.8 and is addressed to the Commissioner for Patents, P.O. Box													
Attorneys at Law 1450, Alexandria, VA 22313-1450													
595 Shrewsbury Avenue, Suite 100 Shrewsbury, New Jersey 07702 Signature of Person Mailing Correspondence													
732-530-9404 Barbara J. Jackson													
					Tyn		d Name of Person Mailing Correspondence						

.

Sheet 1 of 1 sheet(s)

U.S. Depar	tment	t of Commerce, Pate	Docket No.		Serial No	Serial No.						
(PAS) EOIM	1449	modified)	8377/ETCH/SILICON		۱ 10/666,3 ⁷	10/666,317						
MFORMAT		DISCLOSURE STA	Applicant Mui, et al.		Confirma No.:7907	Confirmation No.:7907						
Use severa	al she	ets if necessary)	Filing Date		Group	Group						
TRADE		Examiner	September 19, 2003		1765	·						
U.S. Paten	t Doc	uments										
*Examiner		Document Number	Issue Date	Applicant(s) Name			Filing Date If Appropriate					
	A1	4,767,496	08/30/1988	Hieber	156	627						
A2		5,798,529	08/25/1998	Wagner	250	492.2						
	А3	5,926,690	07/20/1999	Toprac et al.	438	17						
	A4	5,948,203	09/07/1999	Wang	156	345						
	A5	6,004,706	12/21/1999	Ausschnitt et al.	430	30						
	A6	6,027,842	02/22/2000	Ausschnitt et al.	430	30						
	A7	6,161,054	12/12/2000	Rosenthal et al.	700	121						
	A8	6,245,581	06/12/2001	Bonser et al.	438	8						
	A9	6,424,417	07/23/2002	Cohen et al.	356	388						
	A10	6,486,492	11/26/2002	Su	257	48						
	A11	2002/0171828	11/21/2002	Cohen et al.	356	328	07/01/2002					
Foreign Pa	tent l	Documents						= ****				
*Examiner Initial		Document Number	Date	Country	Class	Subclass	Translation YES NO					
	D4						TES					
	B1											
OTHER AR	B2			_	<u></u>							
*Examiner		Including Author, Titl	e, Date, Pertine	nt Pages, Etc.								
	C1	Lee, et al., "Analysis of Reflectometry and Ellipsometry Data from Patterned Structures," Characterization and Metrology for UCSI Technology: 1998 International Conference, Seiler, et al., eds., pg 331-335										
	C2	Raymond, "Angle-resolved scatterometry for semiconductor manufacture,", Microlithography World, Winter 2000.										
	СЗ	Toprac, A., "AMD's Advanced Process Control of Ply-Gate Critical Dimension," Proc. SPIE Vol 3882, pg 62-65, Sept, 1999.										
	C4	Yang, et al., "Line-profile and Critical Dimension Measurements Using a Normal Incidence Optical Metrology System," Proceedings of SPIE Vol. 4689, March 2002,										
Examiner					Date Con	sidered						
*EXAMINER citation if not	: Initia	I if reference considerent	ed, whether or no	ot citation is in confo e copy of this form w	rmance with	MPEP 609; munication to	Draw line thro	ugh				